



**Keynote speaker:**

**Traian Cornel Cucu**

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Traian Cucu is presently leading the Global Applications and Technologies Expert Group at Alpha Assembly Solutions. He was assigned to oversee the new applications and technologies developments which are part of the full solutions offering for the SMT and die attach markets. He received his B.Sc degree from “Politehnica” University of Timisoara, Faculty of Electrical and Power Engineering, Specialization: Industrial Power Systems and his Ph.D. from Politehnica University of Bucharest, Faculty of Electronics, Telecommunications and Information Technologies, Specialization: Electronic Technology. He was part of the technical team from Cookson Electronics that was implementing tin-lead SMT process in late 1990s during the transition from THT to SMT. Early 2000s he was involved in the development and implementation of the lead-free technology for both wave and SMT processes, working for Cookson Electronics and Brady. He was working with major mobile phone OEMs in order to implement new processes that will enable a quicker transition to finer pitch designs and 3D assembly systems for the next generation devices. He was also actively involved, while working with Brady, in the process traceability in electronics with a big accent on the automotive industry. As part of the Alpha technical team he was continuing his work in the assembly process focusing on tin-lead and lead-free processes for automotive. From 2013, as Global Product Manager for Solder Paste he was in charge of solder paste product development, overseeing the product development programs and directing Alpha’s global solder paste strategy, during a period of 4 years. During that period he was directly involved in new solder paste chemistry platforms developments, being part of the R&D team that have been granted a patent for a new approach in solder paste chemistry. Since 2017 he is part of the R&D department, leading the G.A.T.E. Group.